ATTENTION

OBSERVE PRECAUTIONS
FOR HANDLING
ELECTROSTATIC
DISCHARGE
SENSITIVE
DEVICES

Features

- •LOW POWER CONSUMPTION.
- •CABINED VIEWING ANGLE.
- •IDEAL FOR BACKLIGHT AND INDICATOR.
- PACKAGE: 500PCS / BAG.

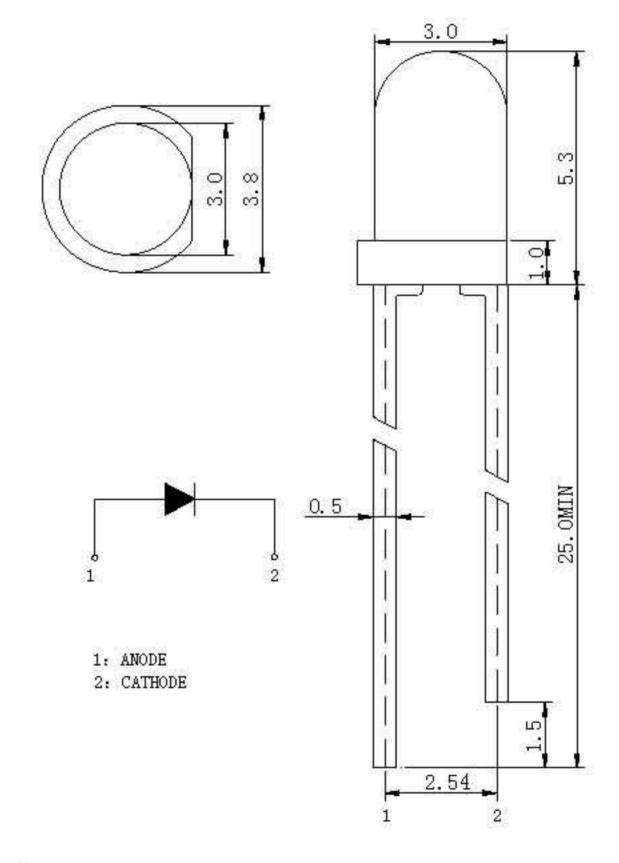
Package Dimensions

308U57GC-15



Description

This devices are made with TS InGaN.



Torlerance	Dimension Torlerance (UNIT:mm)			
Grade	0.5~3	3~6	6~30	30~120
Medium(m)	±0.1	± 0.1	±0.2	±0.3
Chip		Lens Color		
Material	Emitting Color	Water Clear		
InGaN/SiC	Green			

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■ Absolute Maximum Rating

ltem	Symbol	Absolute Maximum Rating	Unit	
Forward Current	lF	20	mΑ	
Peak Forward Current*	IFP	100	mA	
Reverse Voltage	VR	5	V	
Power Dissipation	Po	80	mW	
Electrostatic discharge	Esd	800	V	
Operation Temperature	Topr	-25∽+80	$^{\circ}\! \mathbb{C}$	
Storage Temperature	Tstg	-5∽+45	$^{\circ}\!\mathbb{C}$	
Lead Soldering Temperature*	Tsol	Max. 260°C for 5sec №	lax.	

^{*}IFP Conditions: Pulse Width≤10msec

■ Typical Optical/ Electrical Characteristics

ltem	Symbol	Condition	Min.	Тур.	Max.	Unit
Forward Voltage	VF		2.8	3.2	3.6	V
50% Power Angle	20 1/2		88	25	1995	deg
Luminous Intensity	lv	I _F =20mA	7000	10000	88	mcd
Prcp Wavelength	λD		515	(##)	520	nm
Recommend Forward Current	lr(rec)			×	20	mA
Reverse Current	lr	Vr=5V		15.51	10	uA

Notes:

- 1.Absolute maximum ratings Ta=25°C.
- 2. Tolerance of measurement of forward voltage \pm 0.1 V.
- 3. Tolerance of measurement of peak Wavelength \pm 2.0 nm.
- 4. Tolerance of measurement of luminous intensity $\pm\,$ 15%.
- 5. Tolerance of measurement of angle intensity \pm 15%.

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^{*}Tsol Conditions: 3mm from the base of the epoxy bulb

■ Reliability Performance

Test Items And Result

Test Classification	Test Item	Test Conditions	Test Duration	Sample Size	AC/RE
Life Test	Room Temperature DC Operating Life Test	Ta=25°C±5°C, IF=20mA	1000 hrs	22 pcs	0/1
Environment Test	Thermal Shock Test	-10°C±5°C++100°C±5°C 5min. 10sec. 5min.	50 cycles	22 pcs	0/1
	Temperature Cycle Test	-40°C±5°C+→+85°C±5°C 30min. 5min. 30min.	50 cycles	22 pcs	0/1
	High Temperature & High Humidity Test	Ta=85℃±5℃ RH =85%±0.5 %RH	1000 hrs	22 pcs	0/1
	High Temperature Storage	Ta=100°C±5°C	1000 hrs	22 pcs	0/1
	Low Temperature Storage	Ta=-55°C±5°C	1000 hrs	22 pcs	0/1
Mechanical Test	Resistance to Soldering Heat	Ta=230°C±5°C	5sec.	22 pcs	0/1
	Lead Integrity	Load 2.5N(0.25kgf) 0° ~ 90° ~0°	3times	22 pcs	0/1

30°

40°

50°

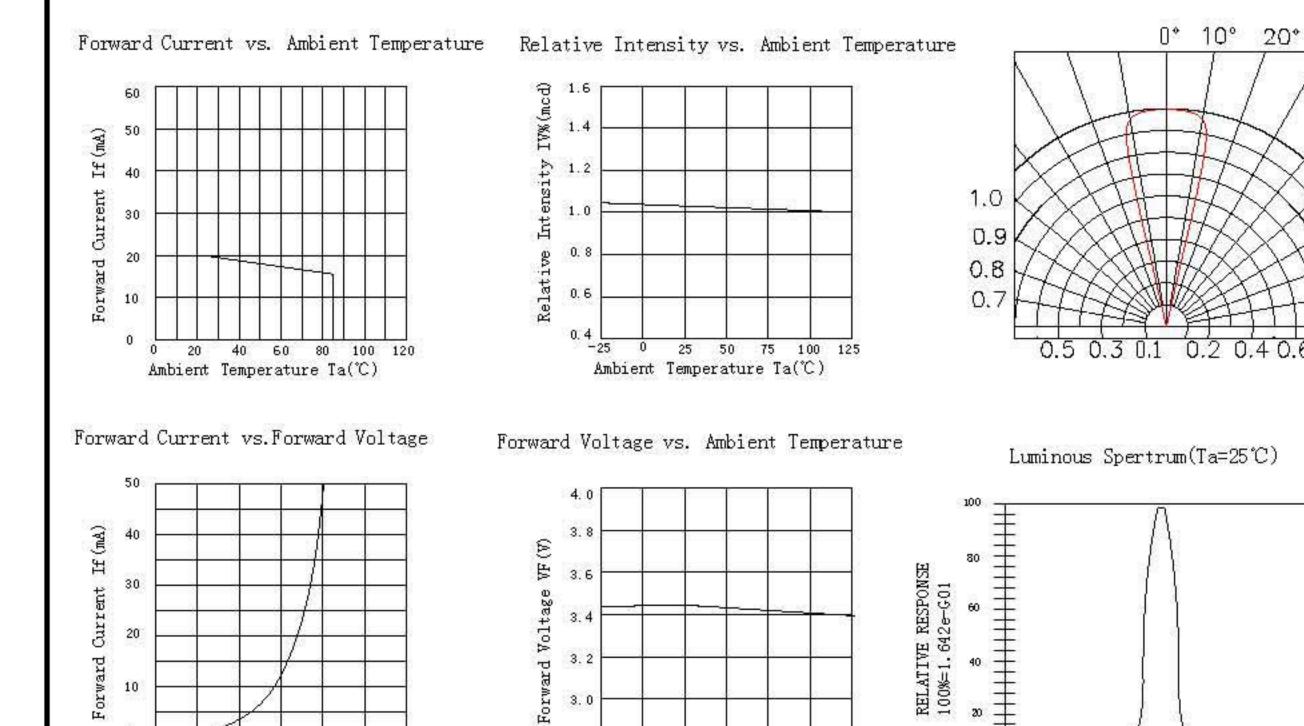
60°

70°

80°

90°

SPECTRAL RADIANCE



3.4

3.2

3.0

20

Forward Voltage VF(V)



25 50 75 100 125

Ambient Temperature Ta(°C)

Soldering:

Manual Of Soldering

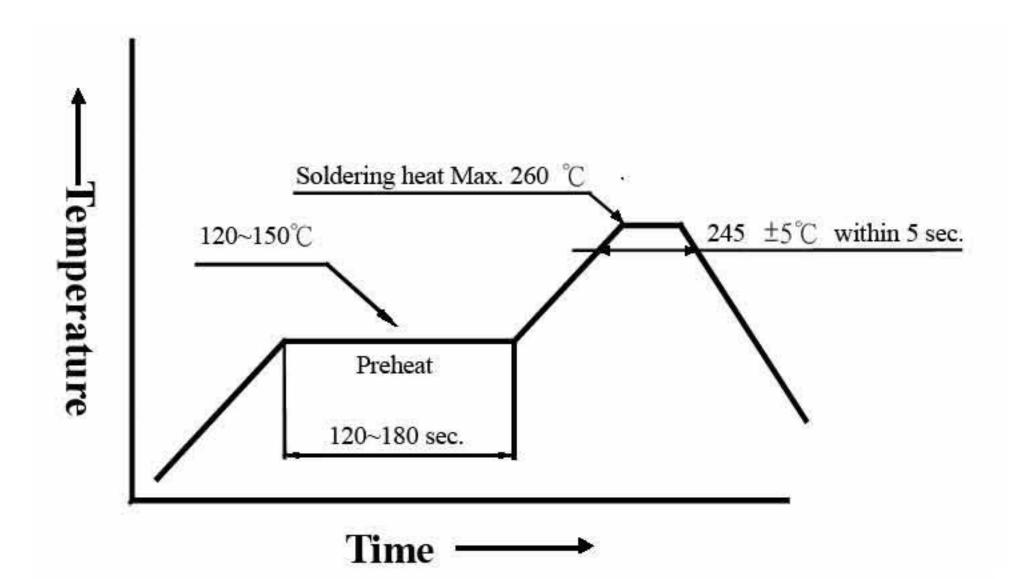
The temperature of the iron tip should not be higher than $260^{\circ}\text{C}(500^{\circ}\text{F})$ and Soldering within 3 seconds per solder-land is to be observed.

DIP soldering (Wave Soldering):

Preheating:120°C~150°C, within 120~180 sec.

Operation heating:245°C±5°C within 5 sec.260°C (Max)

Gradual Cooling (Avoid quenching).



Handling:

Care must be taken not to cause to the epoxy resin portion of LED while it is exposed to high temperature. Care must be taken not rub the epoxy resin portion of LED with hard or sharp article such as the sand blast and the metal hook.

Care must be taken there should be more than 3mm from jointing point to the epoxy resin.

Notes for designing:

Care must be taken to provide the current limiting resistor in the circuit so as to drive the LED within the rated figures. Also caution should be taken not to overload LED with exorbitant voltage at the turning ON and OFF of the circuit.

When using the pulse drive care must be taken to keep the average current within the rated figures .Also the circuit should be designed so as be subjected to reverse voltage when turning off the LED.

Storage:

In order to avoid the absorption of moisture . it is recommended to solder LED as soon as possible after unpacking the sealed envelope.

If the envelope is still packed to store it in the environment as following:

Temperature:-5°C~45°C(23°F~113°F)Humidity: RH 60% Max.

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